

## PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Sun Ha HWANG	12/09/2008
RECEIVING PARTY DATA	
Name:	STS SEMICONDUCTOR & TELECOMMUNICATIONS CO., LTD.
Street Address:	555-9 Baekseok-dong
Internal Address:	Cheonan-city
City:	Chungcheongnam-Do
State/Country:	REPUBLIC OF KOREA
Postal Code:	331-220
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12393651
CORRESPONDENCE DATA	
Fax Number:	(303)499-8089
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Phone:	3034998080
Email:	rfriedland@greenwin.com
Correspondent Name:	Ronald Friedland
Address Line 1:	4875 Pearl East Circle, Suite 200
Address Line 4:	Boulder, COLORADO 80301
ATTORNEY DOCKET NUMBER:	225-08
NAME OF SUBMITTER:	GARY B. CHAPMAN
Total Attachments: 3 source=225-08_US_exd_assignment#page1.tif source=225-08_US_exd_assignment#page2.tif source=225-08_US_exd_assignment#page3.tif	

CH 12393651 \$40.00

PATENT

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REEL: 022321 FRAME: 0424

**ASSIGNMENT**

WHEREAS, I, **HWANG, Sun Ha**, residing at 504-1306 Ssangyong-Deranchae Apt, Ssangyong-dong Cheonan-city, Chungcheongnam-Do, 330-090 Rep.of Korea (each herein called "ASSIGNOR"), am an inventor of the invention entitled APPARATUS FOR MANUFACTURING SEMICONDUCTOR PACKAGE FOR WIDE LEAD FRAME AND METHOD OF CONSTRUCTING SEMICONDUCTOR PACKAGE USING THE SAME, for which I have executed an application for a Patent of the United States, filed February 26, 2009, Serial No. 12/393,651;

AND WHEREAS, **STS SEMICONDUCTOR & TELECOMMUNICATIONS CO., LTD.** (herein called "ASSIGNEE"), an entity organized and existing under the laws of the State of Rep.of Korea, having a principal place of business at 555-9 Baekseok-dong, Cheonan-city, Chungcheongnam-Do 331-220 Rep.of Korea desirous of obtaining my entire right, title and interest in, to and under the said invention and the said application;

NOW, THEREFORE, in consideration of my contractual and other legal obligations, and other good and valuable consideration, the receipt of which is hereby acknowledged, I, a said ASSIGNOR, have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives and assigns, my entire right, title and interest in, to and under the said invention, and the said United States Application and all divisions, renewals, continuations and subsequent applications thereof, and all Patents of the United States which may be granted thereon and all reissues and extensions thereof; and all applications for industrial property protection, including, without limitation, all applications for patents, utility models, and designs which may hereafter be filed for said invention in any country or countries foreign to the United States; together with the right to file such applications and the right to claim for the same the priority of said patent applications listed herein and applications thereof and therefrom under The International Union for the Protection of Industrial Property, or any other international agreement or the domestic laws of the country in which any such application and applications thereof and therefrom is filed, as may be applicable; and all forms of industrial property protection, including, without limitation, patents, utility models, inventors' certificates and designs which may be granted for said invention in any country or countries foreign to the United States and all extensions, renewals and reissues thereof;

AND I HEREBY authorize and request the Commissioner of Patents and Trademarks of the United States, and any official of any country or countries foreign to the United States whose duty it is to issue patents or other evidence or forms of industrial property protection on applications as aforesaid, to issue the same to the said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument;

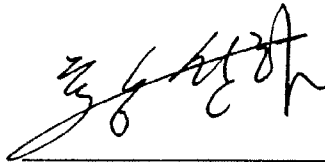
AND I HEREBY covenant and agree that I have full right to convey the entire interest herein assigned, and that I have not executed, and will not execute, any agreement in conflict herewith;

AND I HEREBY authorize the above-mentioned ASSIGNEE or its legal representative to insert in this instrument the filing date and serial number of said application(s) or any other information that may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document;

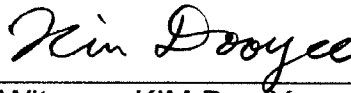
AND I HEREBY further covenant and agree that I will communicate to the said ASSIGNEE, its successors, legal representatives and assigns, any facts known to me respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all continuing and subsequent applications, including divisional, reissue and foreign applications, make all rightful oaths, and generally cooperate and do everything possible to aid the said ASSIGNEE, its successors, legal representatives and assigns, to obtain, maintain, and enforce proper protection for said invention in any and all countries;

IN TESTIMONY WHEREOF, I hereunto set my hand and seal (if applicable) the day and year set opposite my signature.

9 December 2008  
Date

  
\_\_\_\_\_  
HWANG, Sun Ha

9 December 2008  
Date

  
\_\_\_\_\_  
Witness, KIM Doo Yee

Additional Assignors on additional sheets: No